

What is claimed is:

1. A communication device that generates heat, comprising:

5 a high-temperature heat-generating section that generates high-temperature heat;

a first heat-dissipating fin section mounted on said high-temperature heat-generating section, said first heat-dissipating fin section having a heat pipe and fins
10 provided on said heat pipe;

a low-temperature heat-generating section that generates low-temperature heat having a lower temperature than that of the high-temperature heat generated by said high-temperature heat-generating section; and

15 a second heat-dissipating fin section mounted on said low-temperature heat-generating section, said second heat-dissipating fin section having a heat-receiving plate, and fins provided on said heat-receiving plate.

20 2. The communication device as claimed in claim 1, including a protection cover for covering said first heat-dissipating fin section, and

wherein said fins provided on said heat pipe are fixed to said protection cover.

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3. The communication device as claimed in claim 2, wherein said first heat-dissipating fin section has a

heat-receiving plate having said heat pipe disposed thereon, and

wherein said protection cover is fixed to said heat-receiving plate having said heat pipe disposed thereon,
5 via a heat-resistant resin having a low thermal conductivity.

4. The communication device as claimed in claim 2, wherein an inside of said protection cover and said fins
10 of said first heat-dissipating fin section are rigidly fixed to each other by brazing.

5. The communication device as claimed in claim 1, wherein said first heat-dissipating fin section has a
15 heat-receiving plate having said heat pipe disposed thereon,

wherein said high-temperature heat-generating section includes a printed board, and

wherein said printed board is rigidly fixed to said
20 heat-receiving plate having said heat pipe disposed thereon.

6. The communication device as claimed in claim 1, wherein said first heat-dissipating fin section has a
25 heat-receiving plate having said heat pipe disposed thereon,

wherein said high-temperature heat-generating

section includes components that generate heat, and

wherein said components are in contact with said heat-receiving plate having said heat pipe disposed thereon.

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7. The communication device as claimed in claim 6, wherein said components are transistors.

8. The communication device as claimed in claim 1,
10 including an air duct cover for covering said fins of said first heat-dissipating fin section and said fins of said second heat-dissipating fin section to cause air from a cooling fan to pass between said fins of said first heat-dissipating fin section and said fins of said second heat-
15 dissipating fin section.